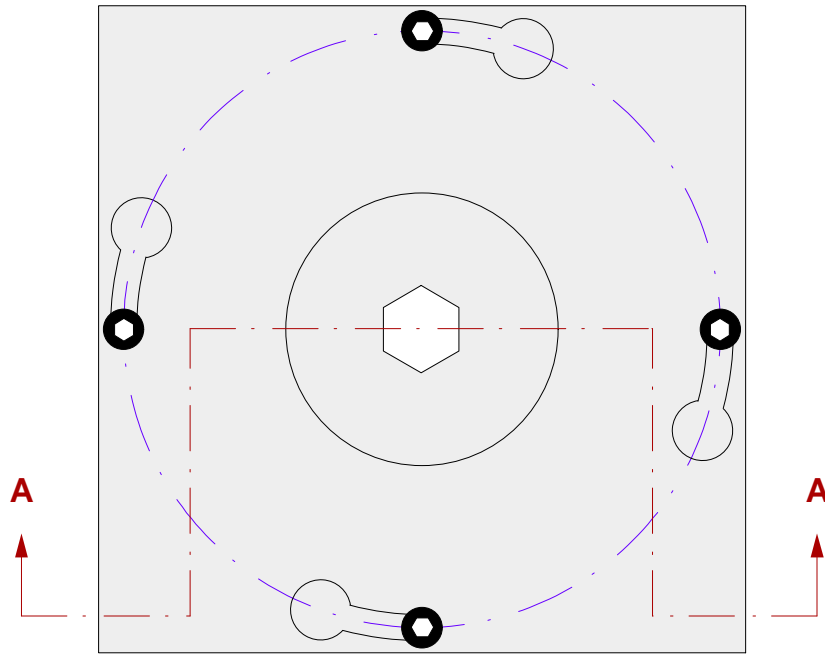


# GHz BGA Socket - Direct mount, solderless

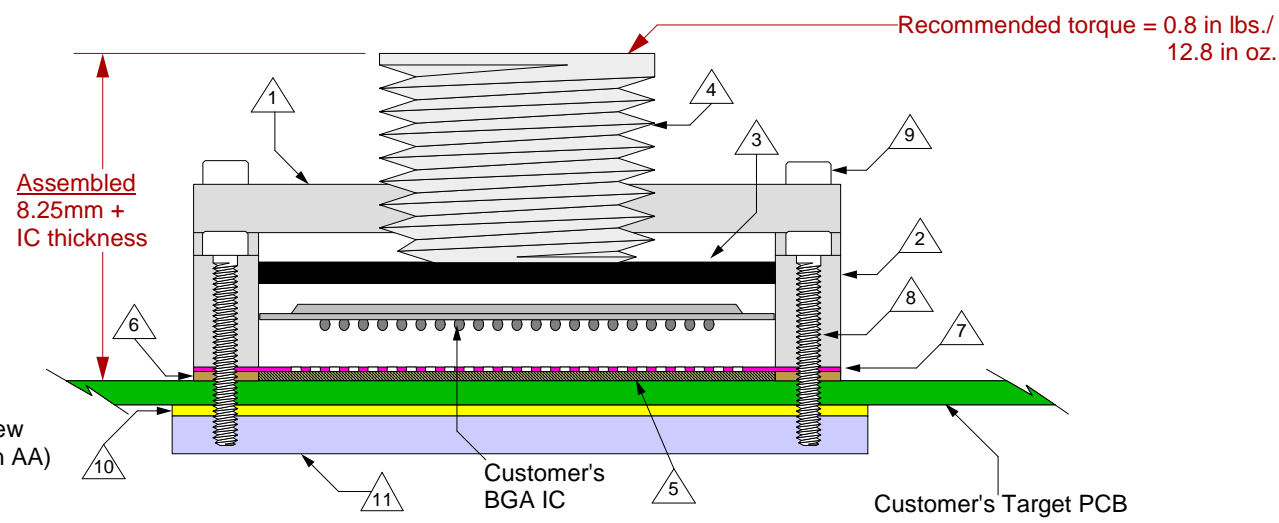
## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

Top View



Side View  
(Section AA)



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.

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- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.

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- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.

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- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.

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- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.

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- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.

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- △ 7 Ball Guide: Kapton polyimide.

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- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.

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- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.

---

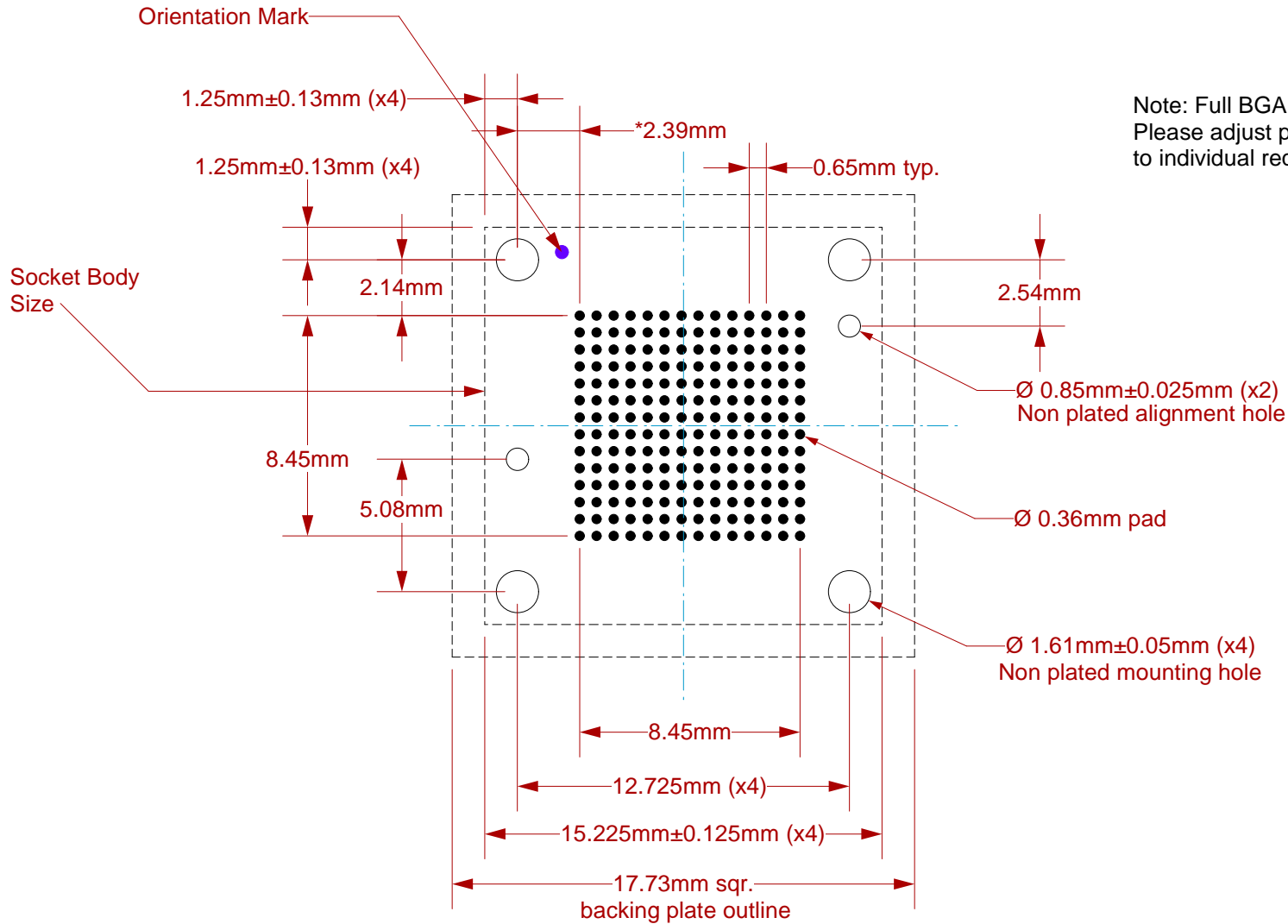
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.

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- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

	<b>SG-BGA-7043 Drawing</b>	Status: Released	Scale: -	Rev: B
	© 2005 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 3/17/05
		File: SG-BGA-7043 Dwg	Modified: 6/2/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.




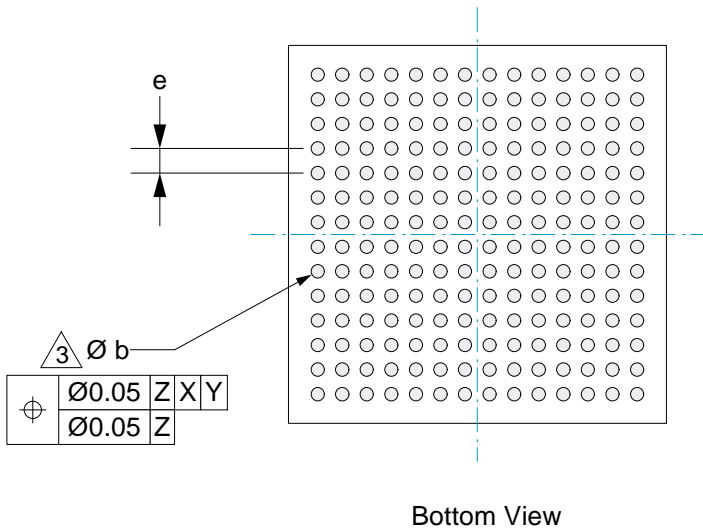
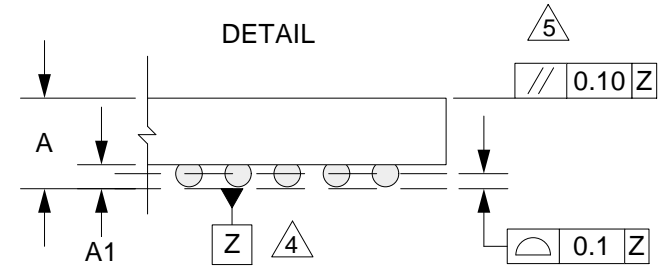
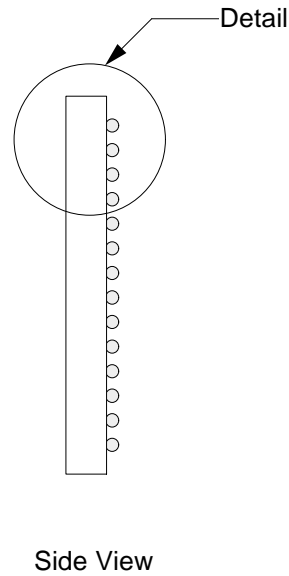
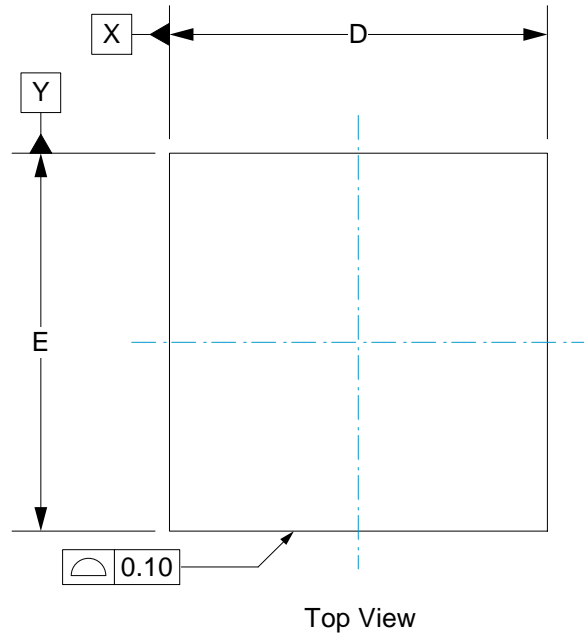
Target PCB Recommendations

Total thickness: 1.6mm min.  
Plating: Gold or Solder finish  
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


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	<p>Drawing: H. Hansen</p>		<p>Date: 3/17/05</p>		
	<p>File: SG-BGA-7043 Dwg</p>		<p>Modified: 6/2/09, AE</p>		



1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- ③ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - ④ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - ⑤ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.4
A1	0.22	0.32
b		0.35
D	10.0 BSC	
E	10.0 BSC	
e	0.65 BSC	

14x14 array

	<b>SG-BGA-7043 Drawing</b>		Status: Released	Scale: 1:0.2	Rev: B	
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				File: SG-BGA-7043 Dwg		Modified: 6/2/09, AE

